

Création et Impression **bristol** - St Pierre d'Allevard - 7 04 76 45 19 47

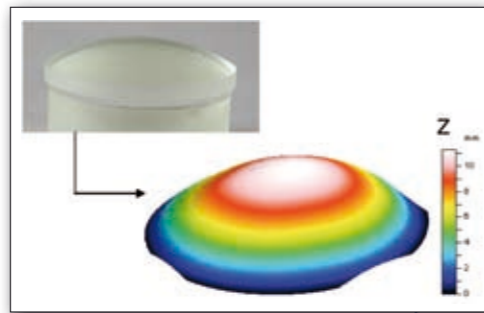
HIGH RESOLUTION NON DESTRUCTIVE TESTING

INSIDIX OFFERS 2 TYPES OF SERVICES

- APPLICATION LABORATORY
Analysis and diagnosis of your samples, carried out by highly qualified staff.
- SYSTEM SALES
Consulting and supply of NDT equipments adapted to your specific applications.

INSIDIX GLOBAL APPROACH MEETS YOUR NEED

- QUALITY CONTROL
- PROCESS DEVELOPMENT
- PERIODIC EXAMINATION DURING PRODUCTION
- FAILURE ANALYSIS



TO CONTACT US

insidix@insidix.com

www.insidix.com

www.TDM-3D.com

INSIDIX

24, rue du Drac - 38180 SEYSSINS - FRANCE
Phone +33 (0)4 38 12 42 80 - Fax +33 (0)4 38 12 03 22



MULTI-TECHNICAL GLOBAL APPROACH

- APPLICATION SERVICES
- SYSTEM SALES

ACOUSTIC
MICROSCOPY
(SAM)

X-RAY
RADIOGRAPHY
2D/3D (CT)

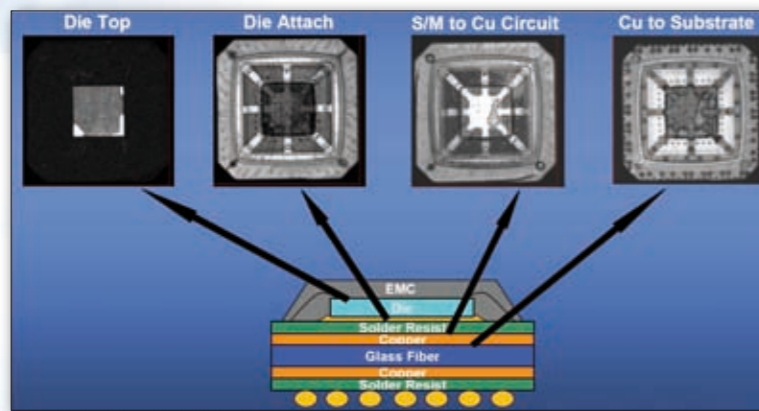
TOPOGRAPHY
AND DEFORMATION
MEASUREMENT (TDM)[®]

X-RAY
MICRO-FLUORESCENCE
(XRF)

INFRA-RED
THERMOGRAPHY
(IR)

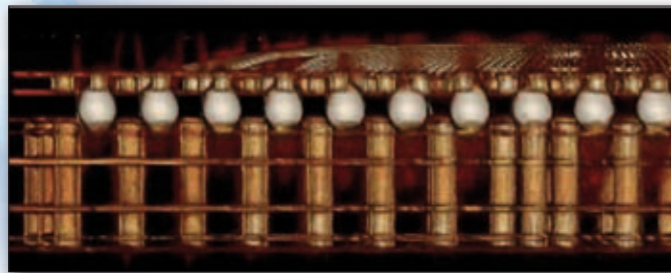
ACOUSTIC MICROSCOPY – SAM

- Interface integrity analysis
- Frequency from 2.5MHz to 300MHz for wide range of applications
- Amplitude, time of flight and phase-shift imaging
- TAMI® Tomography Mode



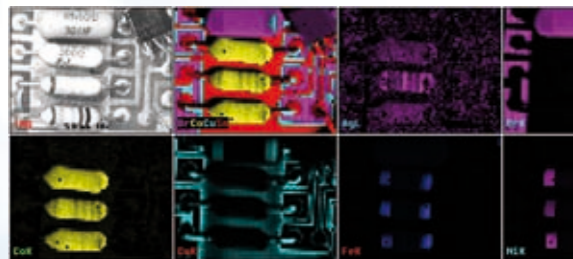
2D AND 3D X-RAY RADIOGRAPHY - μ CT

- 2D radiography analysis ($1\mu\text{m}$ accuracy)
- 3D X-ray tomography (resolution <math>< 5\mu\text{m}</math>)
- Scanning and volume reconstruction time, in less than 5 minutes



X-RAY MICRO-FLUORESCENCE - μ XRF

- Material composition & layer thickness analysis
- Samples can be liquid, solid or powder
- Spatial resolution <math>< 20\mu\text{m}</math>
- Trace detection down to ppm, or even ppb
- Fast element mapping mode



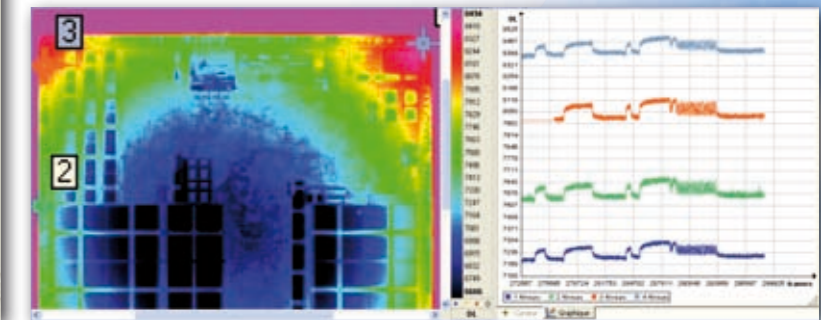
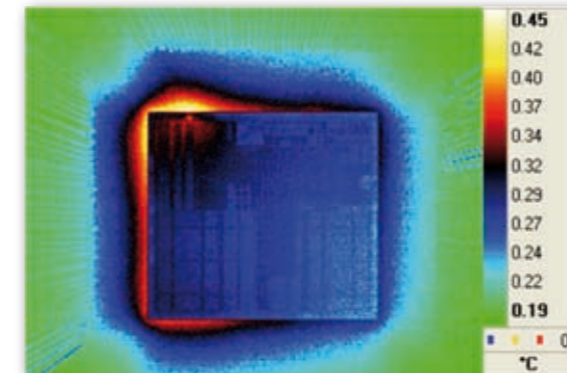
TOPOGRAPHY AND DEFORMATION MEASUREMENTS TDM®

- Warpage analysis under thermal load
- Jedec reflow thermal cycle capability (+ 3°C/sec. to -6°C/sec.)
- In plane CTE (Coefficient Thermal Expansion) measurement
- Full 3D assembly imaging



INFRA-RED THERMOGRAPHY

- Detection of hot spots (shorts, leakage) or heterogeneities, during operation (electric load) or externally heated condition
- Spatial Resolution down to 30 μm
- Thermal resolution down to 10⁻³°C



OEM COMPONENTS

Pulser / Receiver

- High frequency (receiver up to 500MHz)
- Heart of advanced nondestructive testing systems



X-Ray components

- Large product range features
- X-Ray tubes and sources with small focal spot (<math>< 1\mu\text{m}</math> to 400 $\mu\text{m}</math>) and high power (up to 6 kW)$



Digitizer board

- High speed Data Acquisition products with native sampling up to 3 GHz and 2 GB of on-board memory

